

| Ref # | Hits   | Search Query                                   | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|--------|--|---|------------------|---------|------------------|
| S1    | 176    | 702/132.ccls.                                  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:52 |
| S2    | 75     | 702/131.ccls.                                  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:45 |
| S3    | 633    | 702/130.ccls.                                  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:45 |
| S4    | 433    | 702/64.ccls.                                   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:46 |
| S5    | 116993 | temperature and (integrat\$2 or IC) and test   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 13:45 |
| S6    | 24     | S1 and S5                                      | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:51 |
| S7    | 5      | S2 and S5                                      | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:50 |
| S8    | 93     | S3 and S5                                      | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:50 |
| S9    | 49     | S4 and S5                                      | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:50 |
| S10   | 4023   | temperature same (integrat\$2 or IC) same test | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:50 |
| S11   | 8      | S1 and S10                                     | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/05/24 11:52 |

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|-----|-----|------------------------|---|----|-----|------------------|
| S12 | 0   | S2 and S10             | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 11:52 |
| S13 | 18  | S3 and S10             | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 11:51 |
| S14 | 4   | S4 and S10             | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 11:51 |
| S15 | 166 | S10 and "702"/\$.ccls. | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 11:58 |
| S16 | 2   | "20040183588"          | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:00 |
| S17 | 1   | "20050088137"          | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 11:59 |
| S18 | 431 | 327/545.ccls.          | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:00 |
| S19 | 0   | S18 and S10            | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:01 |
| S20 | 402 | 318/806.ccls.          | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:01 |
| S21 | 8   | S18 and S5             | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:01 |
| S22 | 12  | S20 and S5             | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:08 |

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|-----|-------|---|---|----|-----|------------------|
| S23 | 21091 | ((voltage or power or current) with control\$4) and (((semiconductor with substrate) or (integrated adj circuit\$1) or wafer\$1 or chip\$1) with temperature) | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:46 |
| S24 | 4104  | S23 and ((environmental or ambient) near5 temperature)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:47 |
| S25 | 688   | S24 and (voltage near3 bias\$3)   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:17 |
| S26 | 78    | S25 and (thermal near4 resistance)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:16 |
| S27 | 495   | S25 and ((power or voltage) near4 supply)   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:19 |
| S28 | 241   | S25 and ((power or voltage) near4 supply with temperature)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:20 |
| S29 | 228   | S28 and (current with voltage)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 12:20 |
| S30 | 37    | 702/129.ccls.   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:44 |
| S31 | 1     | S30 and (temperature and (integrat\$2 or IC) and test)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:46 |
| S32 | 4207  | 324/765.ccls.   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:46 |
| S33 | 821   | S32 and (temperature and (integrat\$2 or IC) and test)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:46 |

|     |       |   |   |    |     |                  |
|-----|-------|---|---|----|-----|------------------|
| S34 | 192   | S32 and (((voltage or power or current) with control\$4) and (((semiconductor with substrate) or (integrated adj circuit\$1) or wafer\$1 or chip\$1) with temperature)) | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:46 |
| S35 | 36    | S34 and ((environmental or ambient) near5 temperature)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:47 |
| S36 | 21091 | ((voltage or power or current) with control\$4) and (((semiconductor with substrate) or (integrated adj circuit\$1) or wafer\$1 or chip\$1) with temperature)           | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:48 |
| S37 | 4104  | S36 and ((environmental or ambient) near5 temperature)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:48 |
| S38 | 688   | S37 and (voltage near3 bias\$3)   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:48 |
| S39 | 241   | S38 and ((power or voltage) near4 supply with temperature)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:48 |
| S40 | 228   | S39 and (current with voltage)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:48 |
| S41 | 39    | S40 and (junction near5 temperature)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/05/24 13:48 |